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Data Sheet October 2013

N-Channel Logic Level Power MOSFET 60 V, 16 A, 47 $m\Omega$

These are N-Channel power MOSFETs manufactured using a modern process. This process, which uses feature sizes approaching those of LSI integrated circuits gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers, relay drivers and emitter switches for bipolar transistors. This performance is accomplished through a special gate oxide design which provides full rated conductance at gate bias in the 3V to 5V range, thereby facilitating true on-off power control directly from logic level (5V) integrated circuits.

Formerly developmental type TA49027.

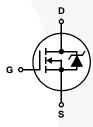
Ordering Information

PART NUMBER	PACKAGE	BRAND		
RFD16N06LESM9A	TO-252AA	16N06LE		

Features

- 16A, 60V
- $r_{DS(ON)} = 0.047\Omega$
- Temperature Compensating PSPICE[®] Model
- Can be Driven Directly from CMOS, NMOS, TTL Circuits
- · Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC TO-252AA



RFD16N06LESM

Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

	RFD16N06LESM	UNITS
Drain to Source Voltage (Note 1)V _{DSS}	60	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1) V_{DGR}	60	V
Gate to Source Voltage	+10, -8	V
Continuous Drain Current	16	Α
Pulsed Drain Current (Note 3)	Refer to Peak Current Curve	
Pulsed Avalanche RatingE _{AS}	Refer to UIS Curve	
Power Dissipation	90	W
Derate Above 25 ^o C	0.606	W/oC
Operating and Storage Temperature	-55 to 175	°С
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	300	°C
Package Body for 10s, See Techbrief 334	260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $150^{\circ}C$.

Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CO	ONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	$I_D = 250 \mu A, V_{GS} = 0 V, Figure 11$		60	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250\mu A, Figure 10$		1	-	3	V
Zero Gate Voltage Drain Current	I _{DSS}	I _{DSS} V _{DS} = 55V, V _{GS} = 0V		-	-	1	μΑ
		V _{DS} = 50V, V _{GS} =	0V, T _C = 150 ^o C	-	-	250	μΑ
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = +10, -8V$		-	-	10	μΑ
Drain to Source On Resistance (Note 2)	r _{DS(ON)}	I _D = 16A, V _{GS} = 5V	1	-	-	0.047	Ω
Turn-On Time	t _{ON}	V_{DD} = 30V, I_{D} = 16A, R_{L} = 1.88Ω, V_{GS} = 5V, R_{GS} = 5Ω Figures 16, 17		-	-	100	ns
Turn-On Delay Time	t _{d(ON)}			-	11	-	ns
Rise Time	t _r			-	60	-	ns
Turn-Off Delay Time	t _d (OFF)			-	48	-	ns
Fall Time	t _f			-	35	-	ns
Turn-Off Time	tOFF			/-	-	115	ns
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 10V	V _{DD} = 48V,	-	51	62	nC
Gate Charge at 5V	Q _{g(5)}	$V_{GS} = 0V \text{ to } 5V$	$I_D = 16A, R_L = 3\Omega$ Figures 18, 19	-	29	35	nC
Threshold Gate Charge	Q _{g(TH)}	$V_{GS} = 0V \text{ to } 1V$		-	1.8	2.6	nC
Input Capacitance	C _{ISS}	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz Figure 12		-	1350	-	pF
Output Capacitance	C _{OSS}			-	300	-	pF
Reverse Transfer Capacitance	C _{RSS}			-	90	-	pF
Thermal Resistance Junction to Case	$R_{ heta JC}$			-	-	1.65	oC/W
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-252AA		-	-	80	°C/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V_{SD}	I _{SD} = 16A	-	-	1.5	V
Diode Reverse Recovery Time	t _{rr}	$I_{SD} = 16A$, $dI_{SD}/dt = 100A/\mu s$	-	-	125	ns

NOTES:

- 2. Pulse Test: Pulse Width ≤300µs, Duty Cycle ≤2%.
- 3. Repetitive Rating: Pulse Width limited by max junction temperature.

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Typical Performance Curves Unless Otherwise Specified

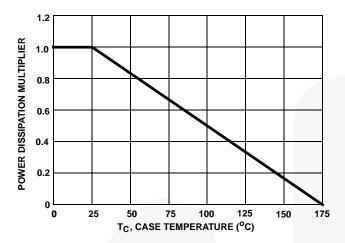


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

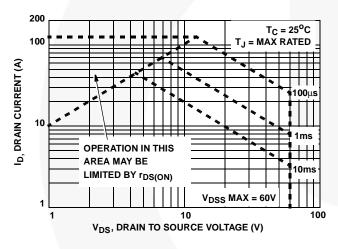


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

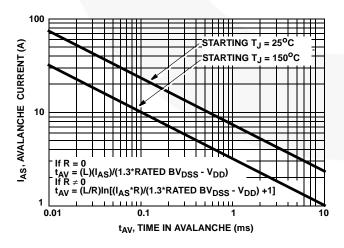


FIGURE 5. UNCLAMPED INDUCTIVE SWITCHING

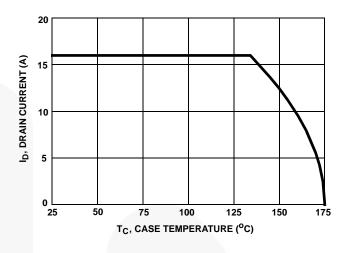


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

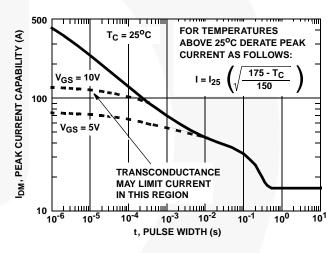


FIGURE 4. PEAK CURRENT CAPABILITY

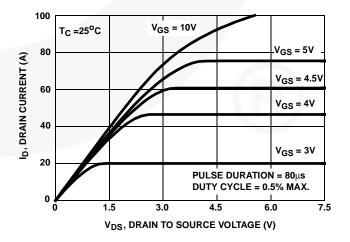


FIGURE 6. SATURATION CHARACTERISTICS

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Typical Performance Curves Unless Otherwise Specified (Continued)

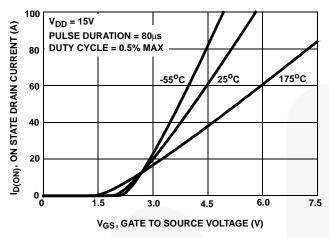


FIGURE 7. TRANSFER CHARACTERISTICS

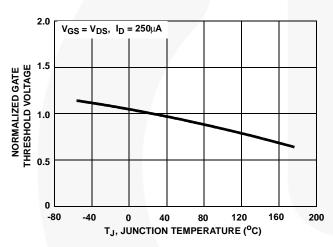


FIGURE 9. NORMALIZED GATE THRESHOLD VOLTAGE vs TEMPERATURE

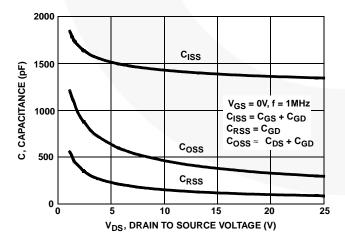


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

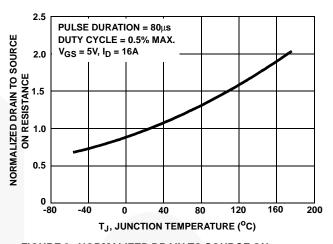


FIGURE 8. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

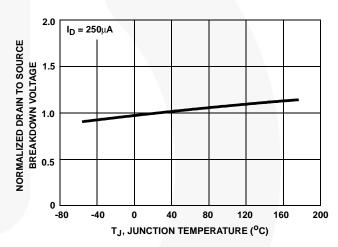
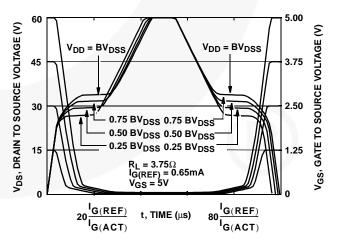


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 12. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

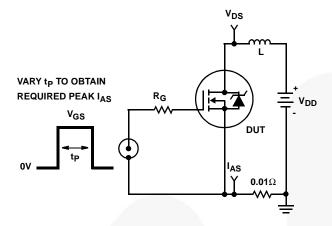


FIGURE 13. UNCLAMPED ENERGY TEST CIRCUIT

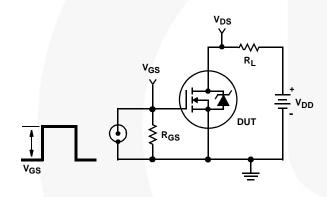


FIGURE 15. SWITCHING TIME TEST CIRCUIT

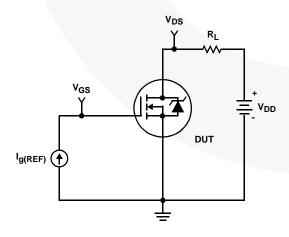


FIGURE 17. GATE CHARGE TEST CIRCUIT

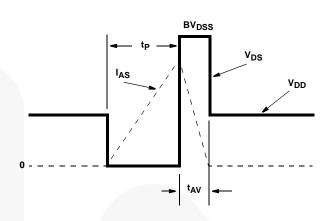


FIGURE 14. UNCLAMPED ENERGY WAVEFORMS

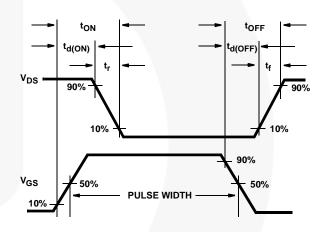


FIGURE 16. RESISTIVE SWITCHING WAVEFORMS

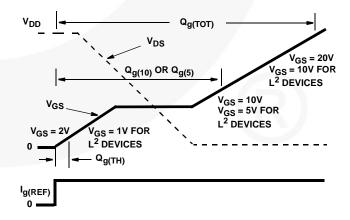
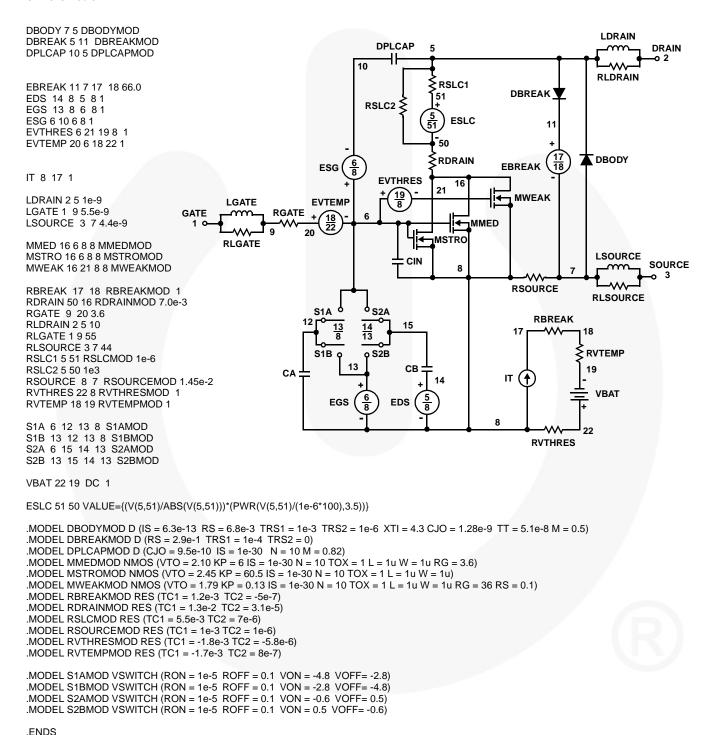


FIGURE 18. GATE CHARGE WAVEFORMS

PSPICE Electrical Model

SUBCKT RFD16N06LESM 2 1 3; rev 8/2/93

CA 12 8 1.46e-9 CB 15 14 1.46e-9 CIN 6 8 1.0e-9



For further discussion of the PSPICE model, consult A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

RFD16N06LESM



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